

Device-Orientation Effects on Multiple-Bit Upset in 65-nm SRAMs



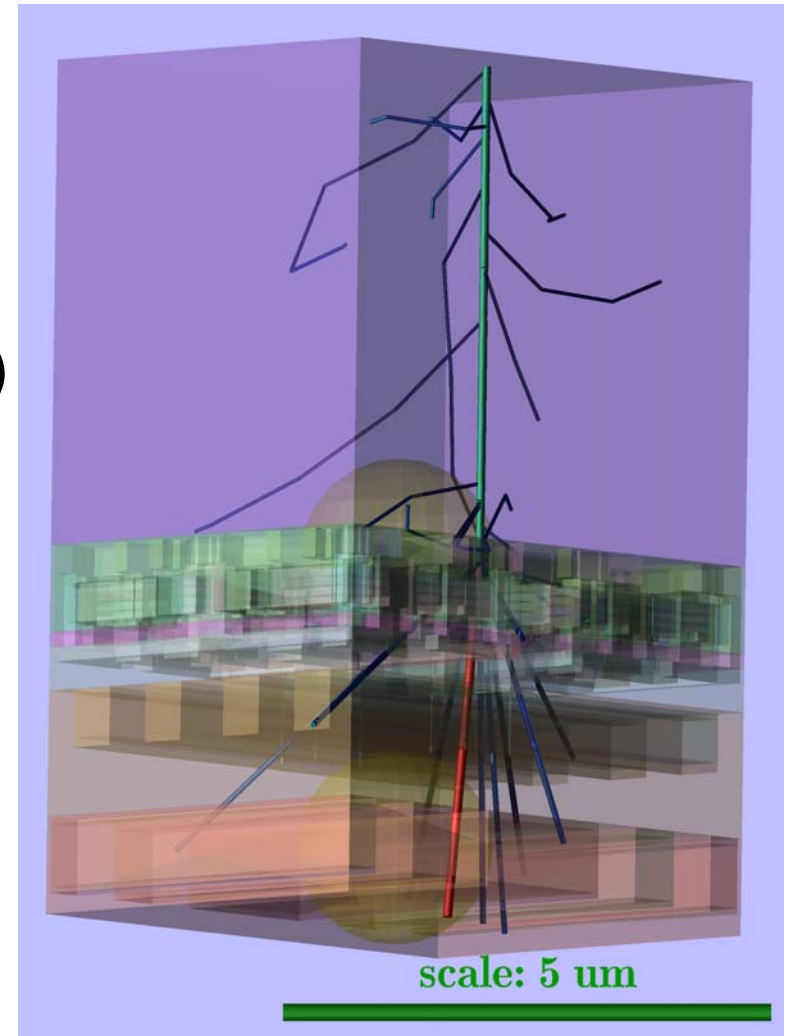
Alan D. Tipton¹, Jonathan A. Pellish¹, John M. Hutson¹, Robert Baumann², Xiaowei Deng¹, Andrew Marshall², Michael A. Xapsos³, Hak S. Kim⁴, Mark R. Friendlich⁴, Michael J. Cam¹, Christina M. Seidleck⁴, Ken A. LaBel³, Marcus H. Mendenhall¹, Robert A. Reed¹, Ronald D. Schrimpf¹, & Robert A. Weller¹

1. Vanderbilt University
2. Texas Instruments
3. NASA-GSFC
4. MEI Technology



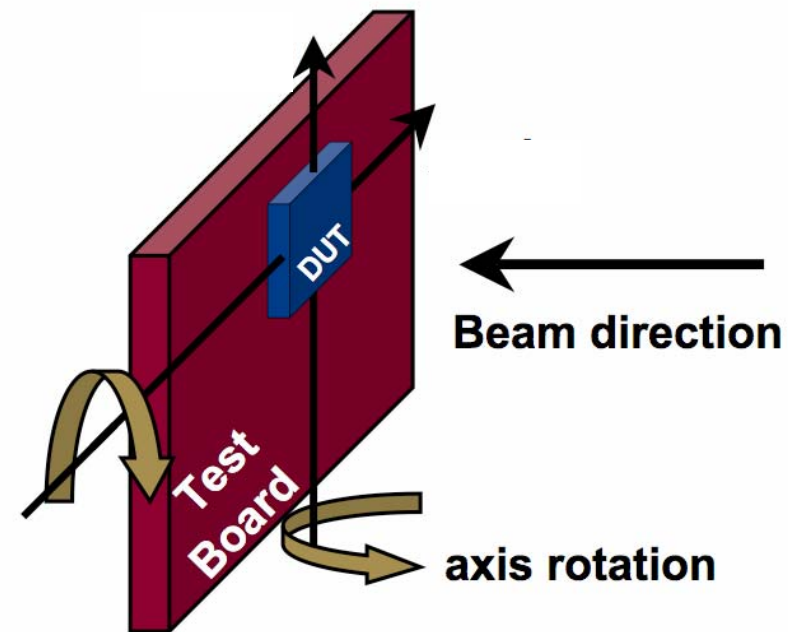
Outline

- Device under test
- Heavy ion irradiations
 - Single event upset (SEU)
 - Multiple-bit upset (MBU)
- Monte-Carlo simulation (MRED)
 - Physical model
 - Environment
 - MBU response
- Conclusion

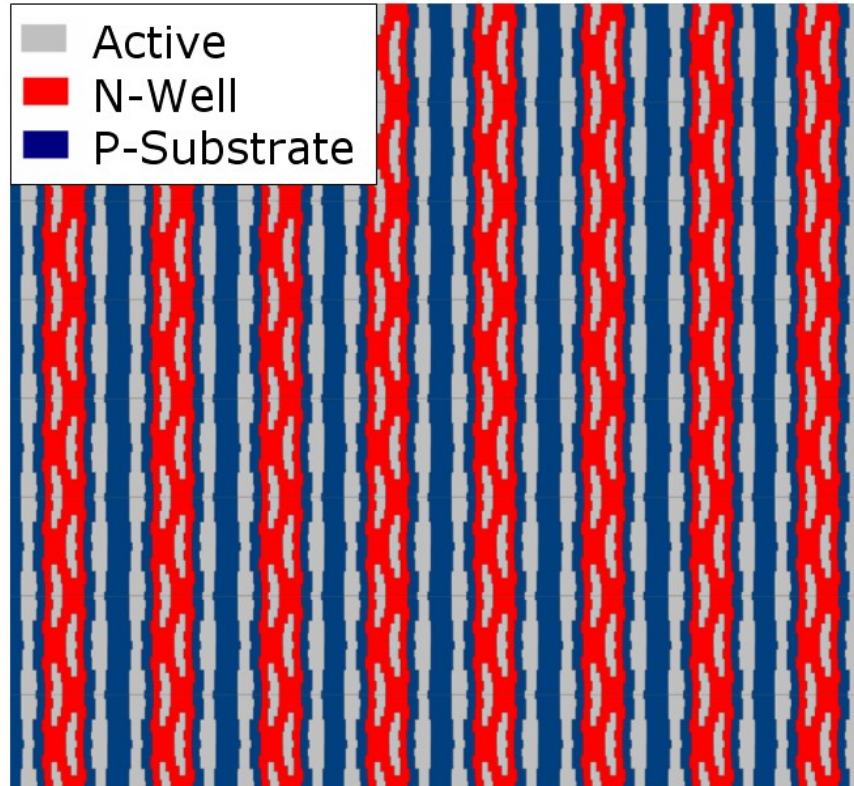


Device under test

- Texas Instruments 65 nm CMOS SRAM
- 4 Mbit memory
- 1.2 V operating voltage
- Irradiations about two axes
- Heavy ions at TAMU

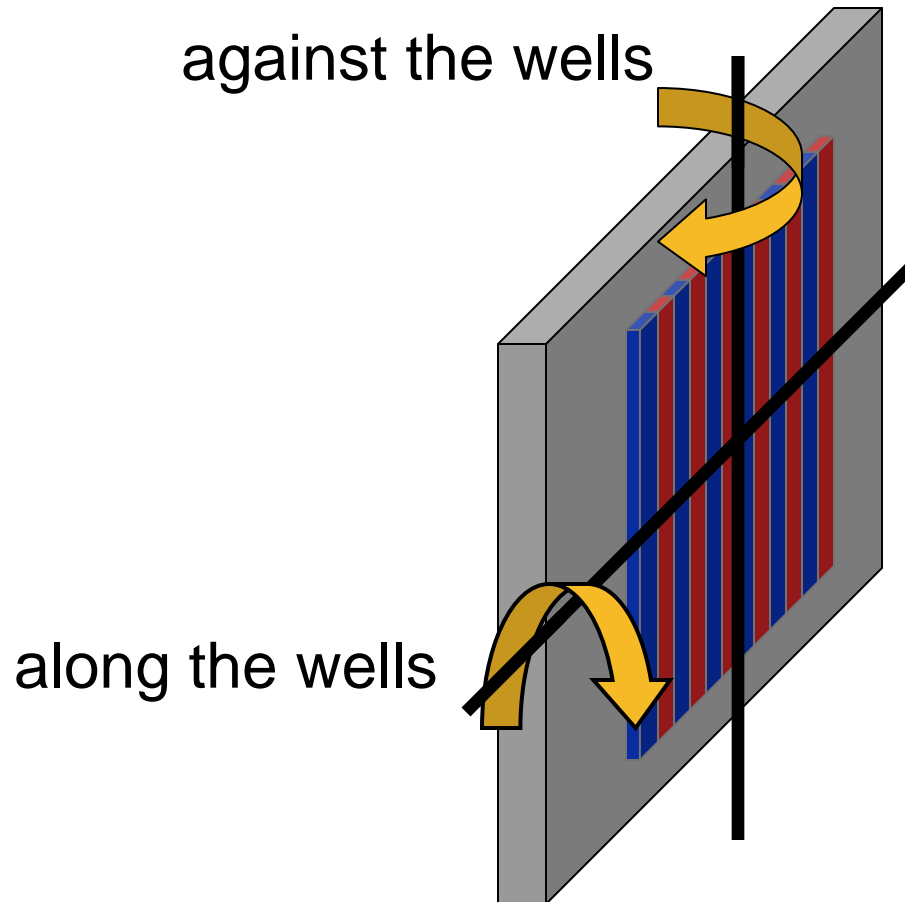


SRAM layout produces alternating columns of wells



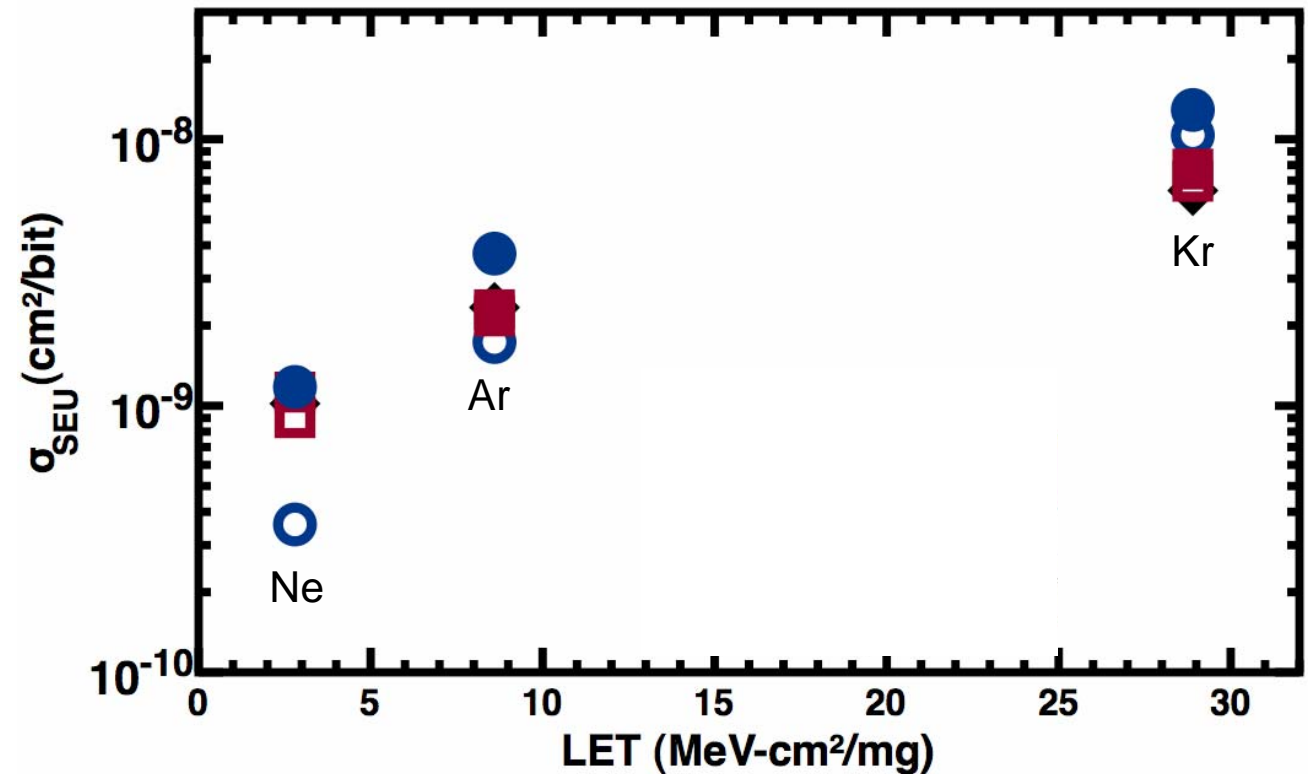
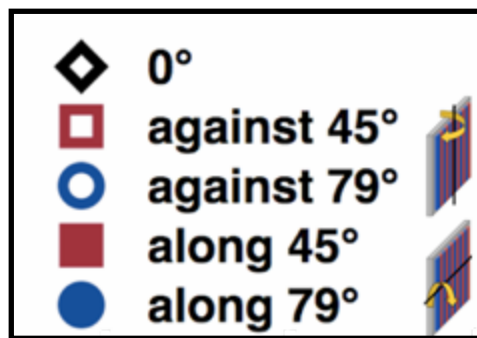
from Hutson *et al.*

Define the device orientation by the wells



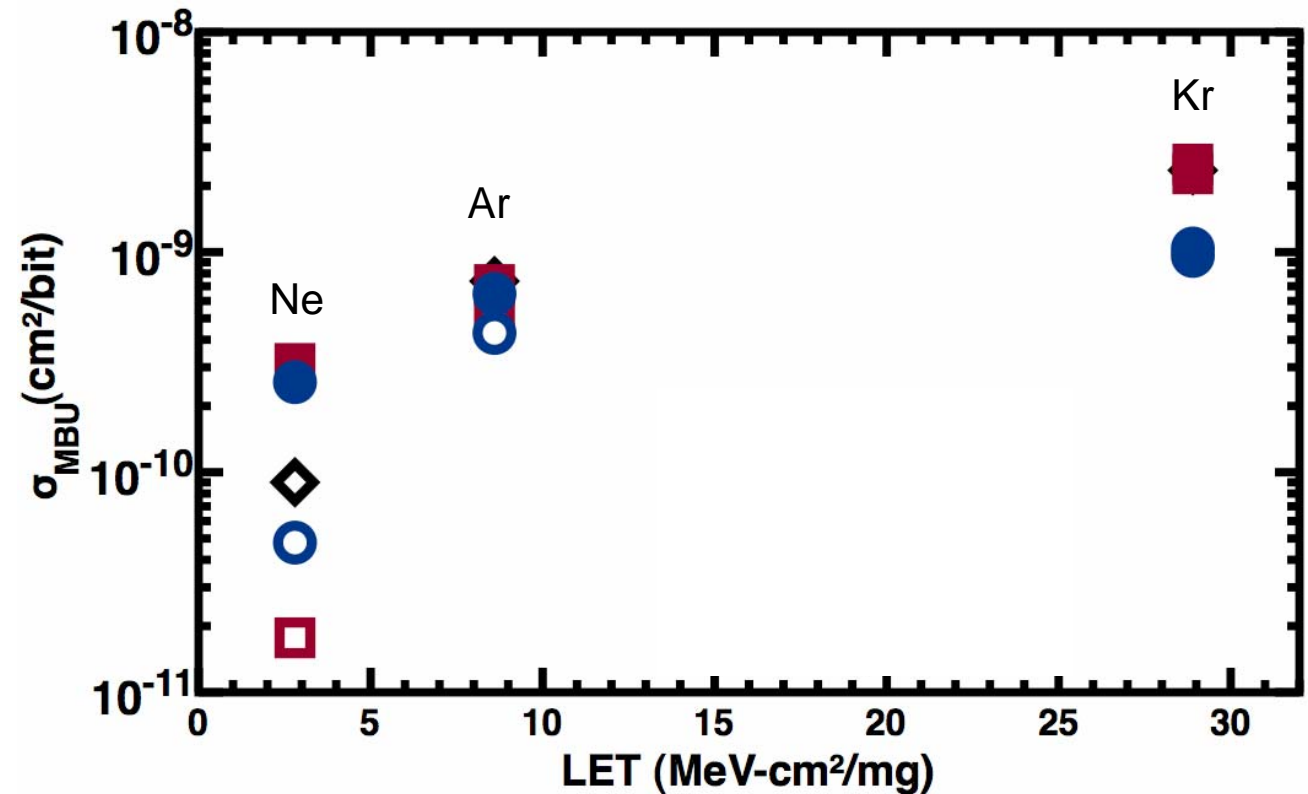
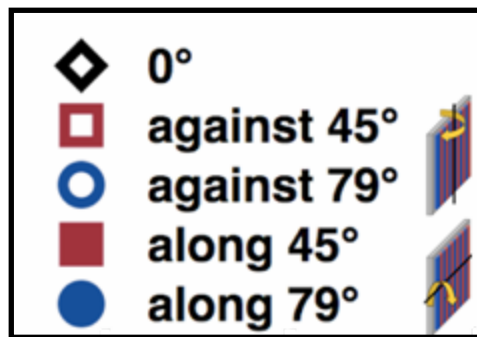
SEU cross section varies little with orientation

- SEU cross section for all bit upsets
- LET values are at top of DUT
- 15 MeV/u tune



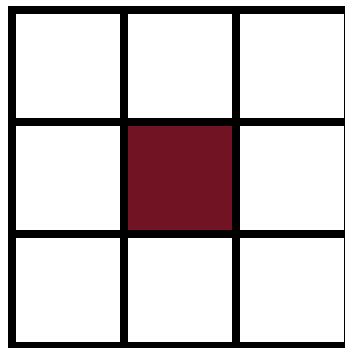
MBU cross section changes with orientation

- MBU events are physically adjacent upsets

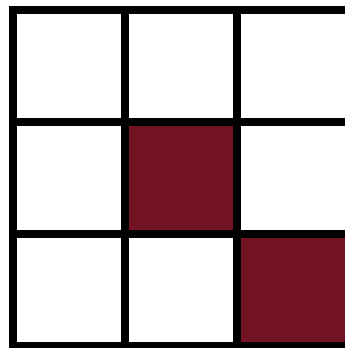


MBU size

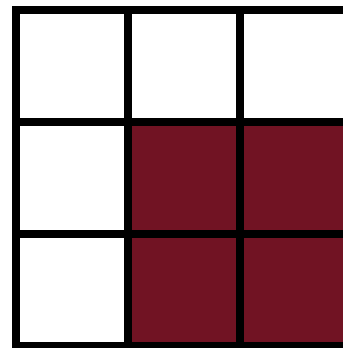
- Size is defined as the number of affected rows or columns
- MBU dimension \equiv affected rows \times affected columns
- Wells run along the columns
- Examples



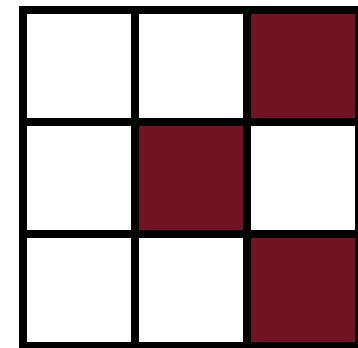
1x1



2x2



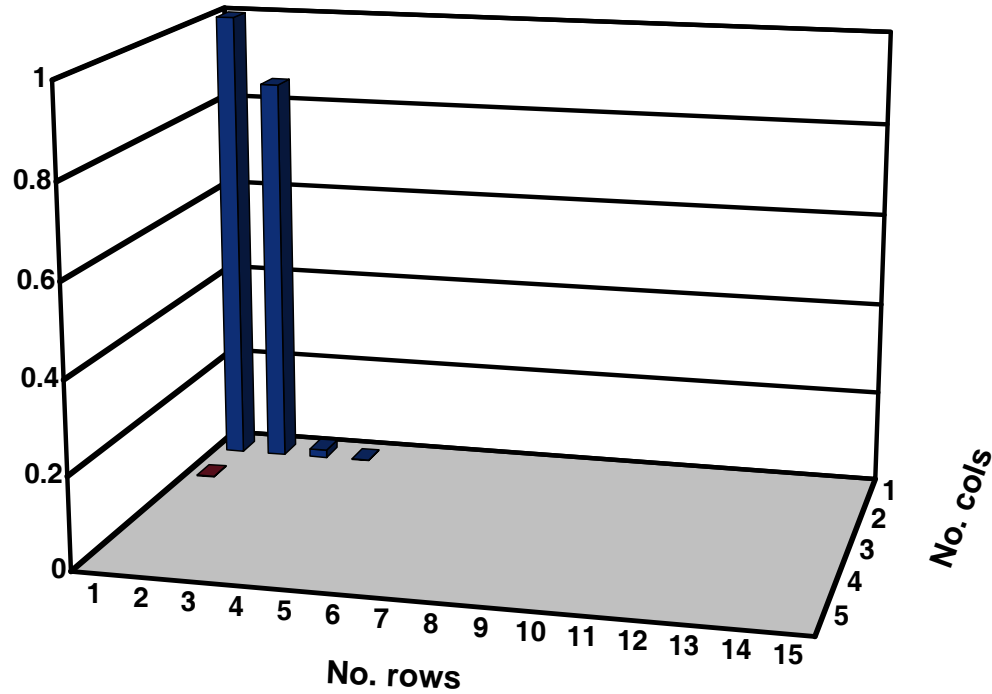
2x2



3x2

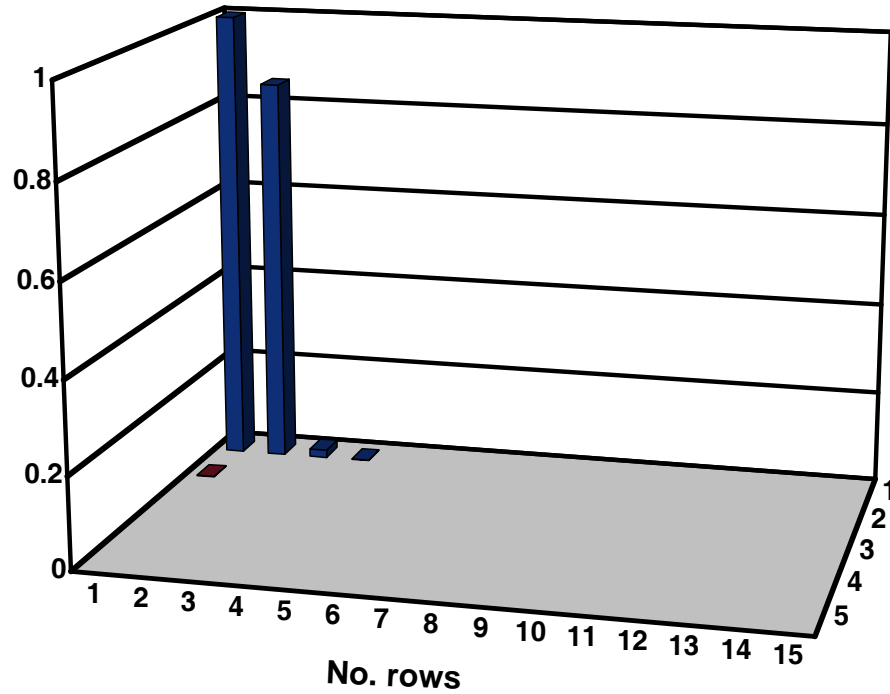
MBU dimension

Ar normal incidence

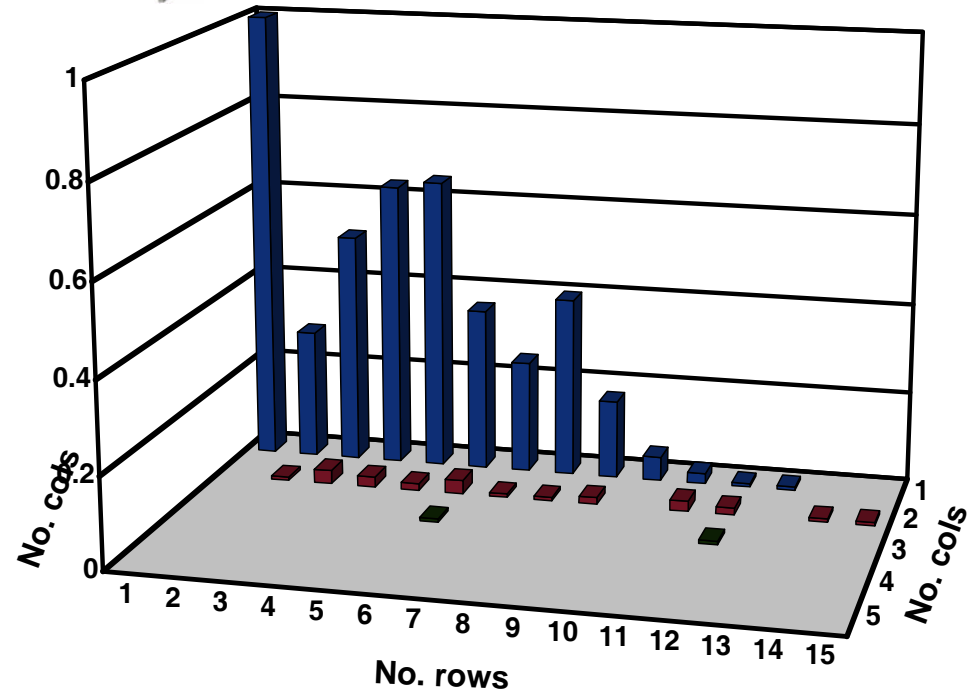


MBU dimension

Ar normal incidence



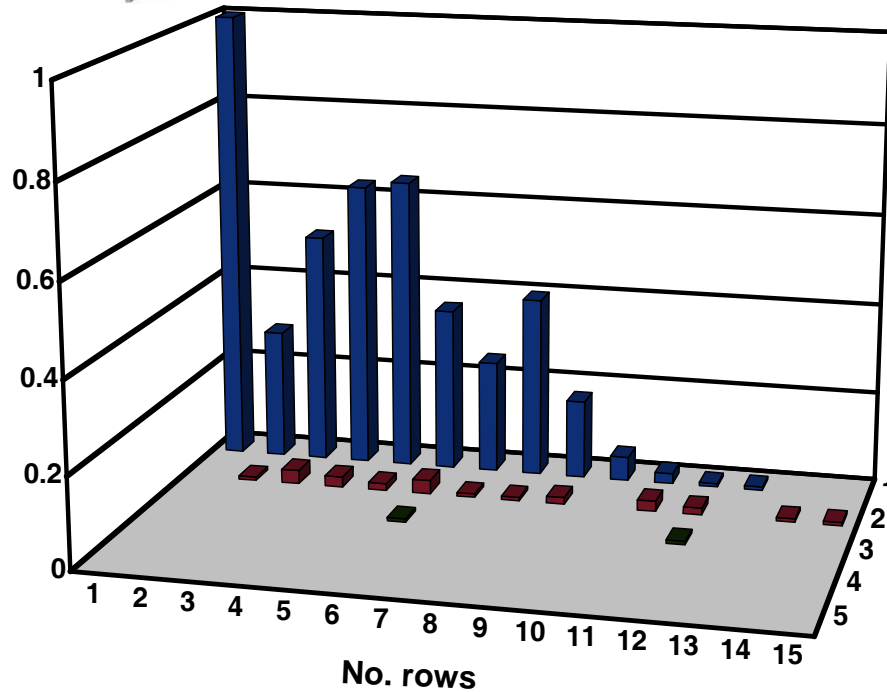
Ar 79° along the wells



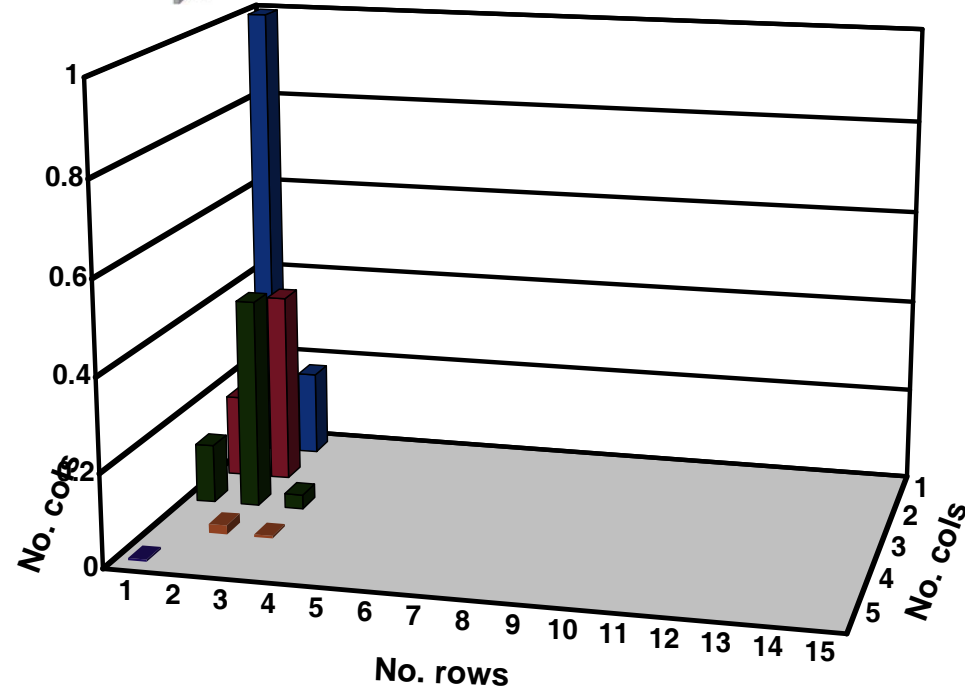
The shape of MBU events depends on orientation



Ar 79° along the wells

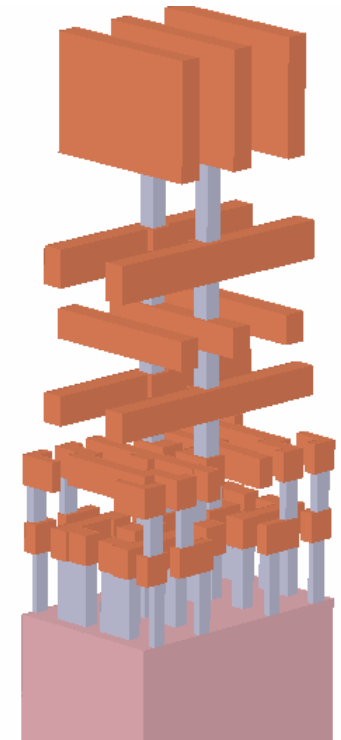


Ar 79° against the wells



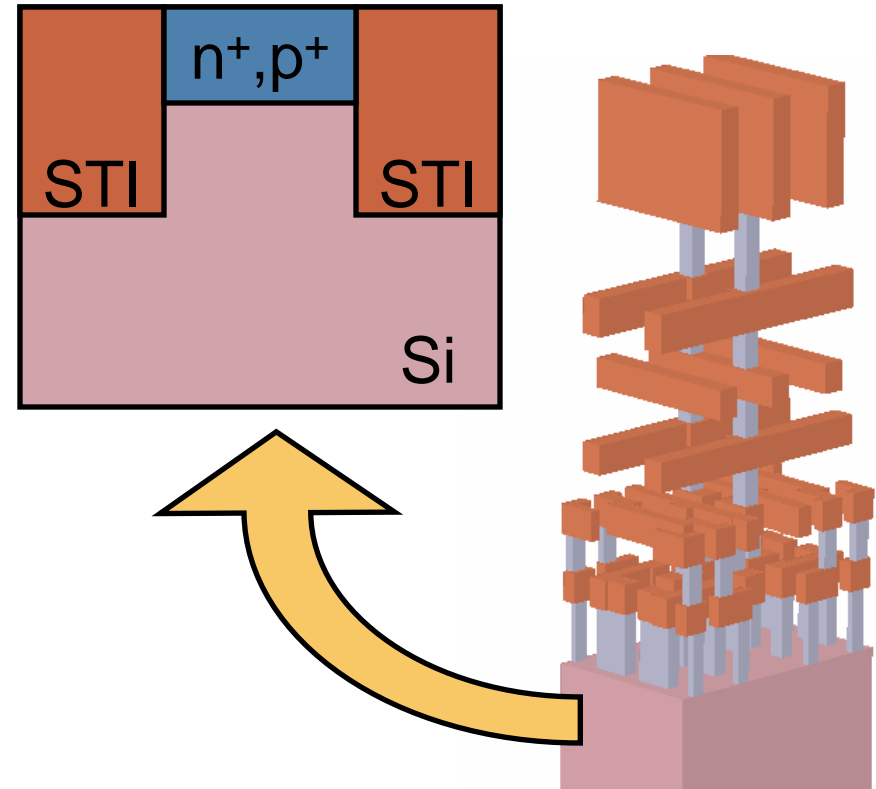
The device was modeled in MRED

- TCAD structure
 - Layout information
 - Metallization



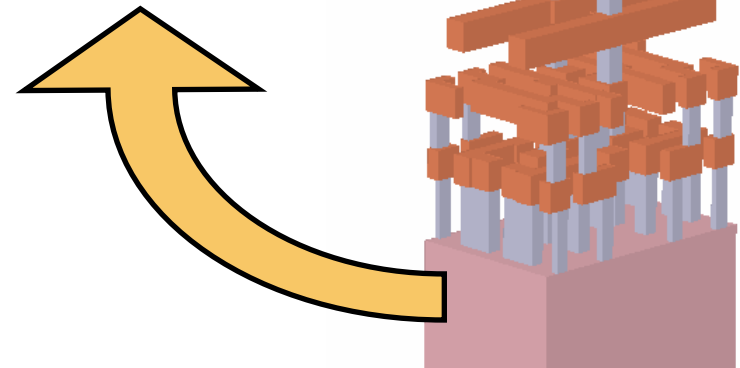
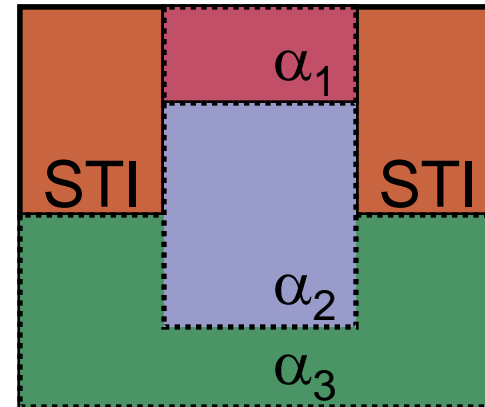
The device was modeled in MRED

- TCAD structure
 - Layout information
 - Metallization
- Sensitive volume
 - Layout and process boundaries
 - Calibrated using TCAD



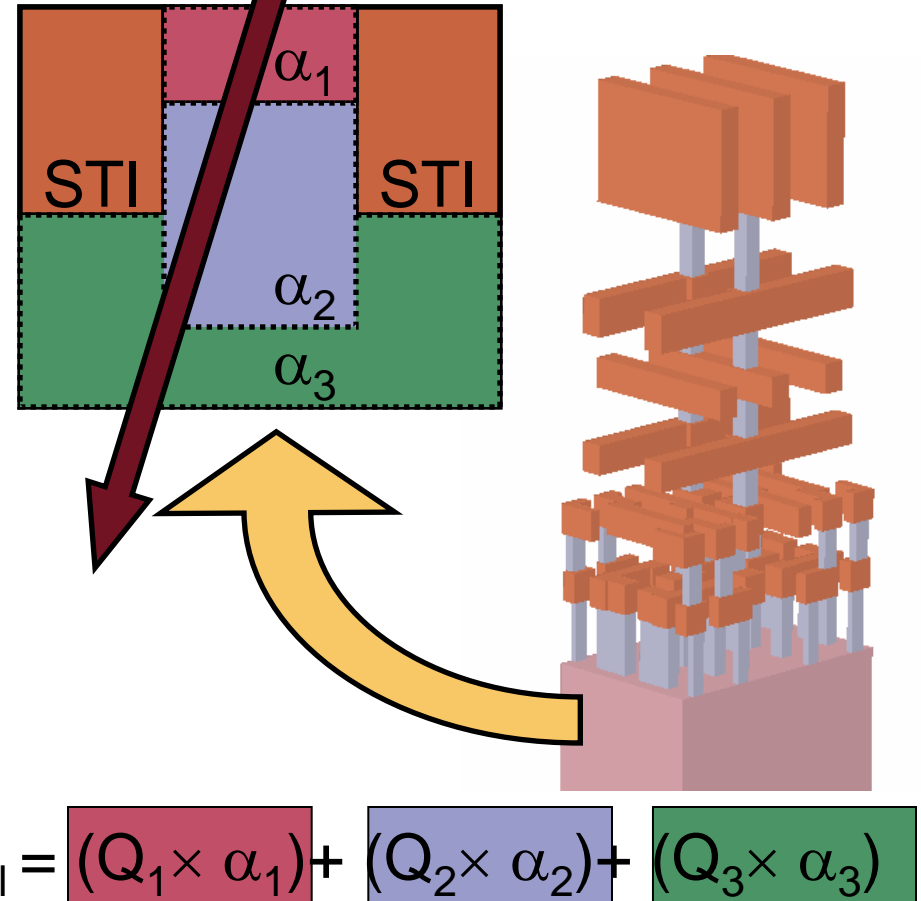
The device was modeled in MRED

- TCAD structure
 - Layout information
 - Metallization
- Sensitive volume
 - Layout and process boundaries
 - Calibrated using TCAD
 - Nested approach
 - Charge collection efficiency, α

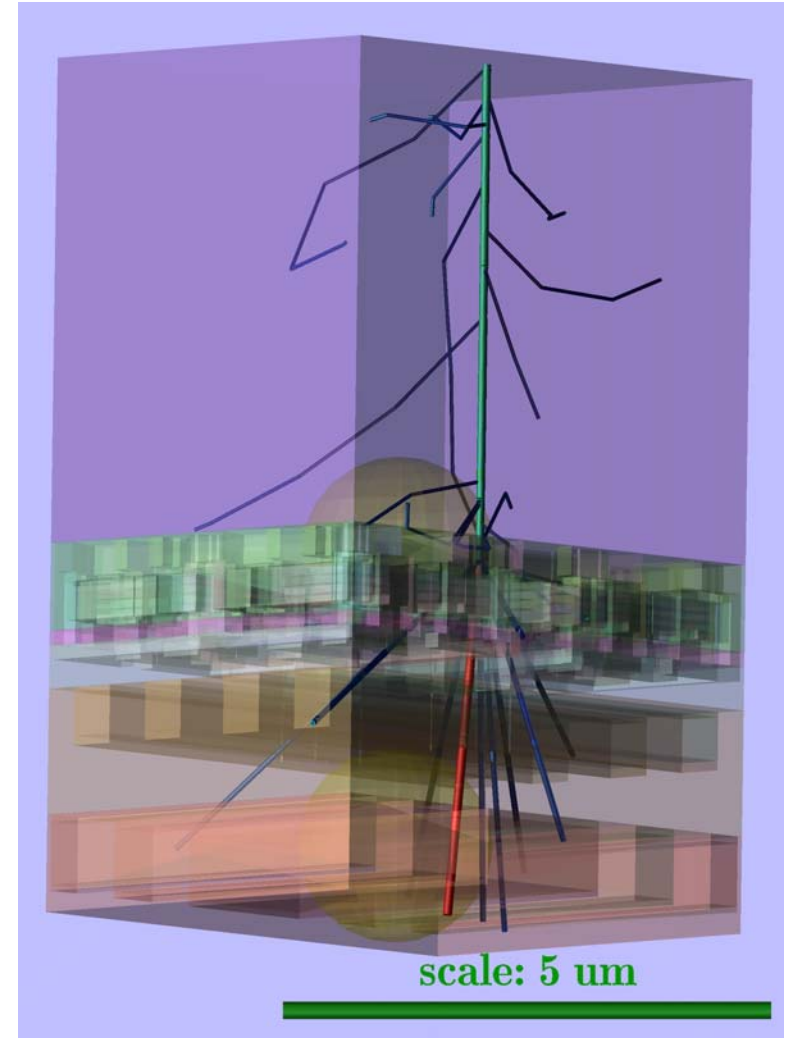
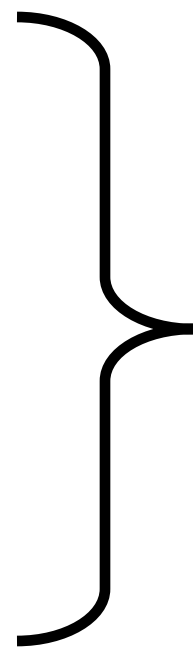
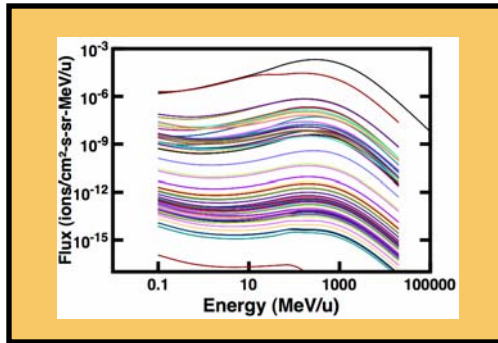
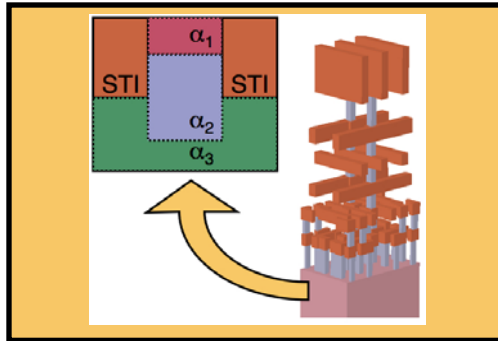


The device was modeled in MRED

- TCAD structure
 - Layout information
 - Metallization
- Sensitive volume
 - Layout and process boundaries
 - Calibrated using TCAD
 - Nested approach
 - Charge collection efficiency, α

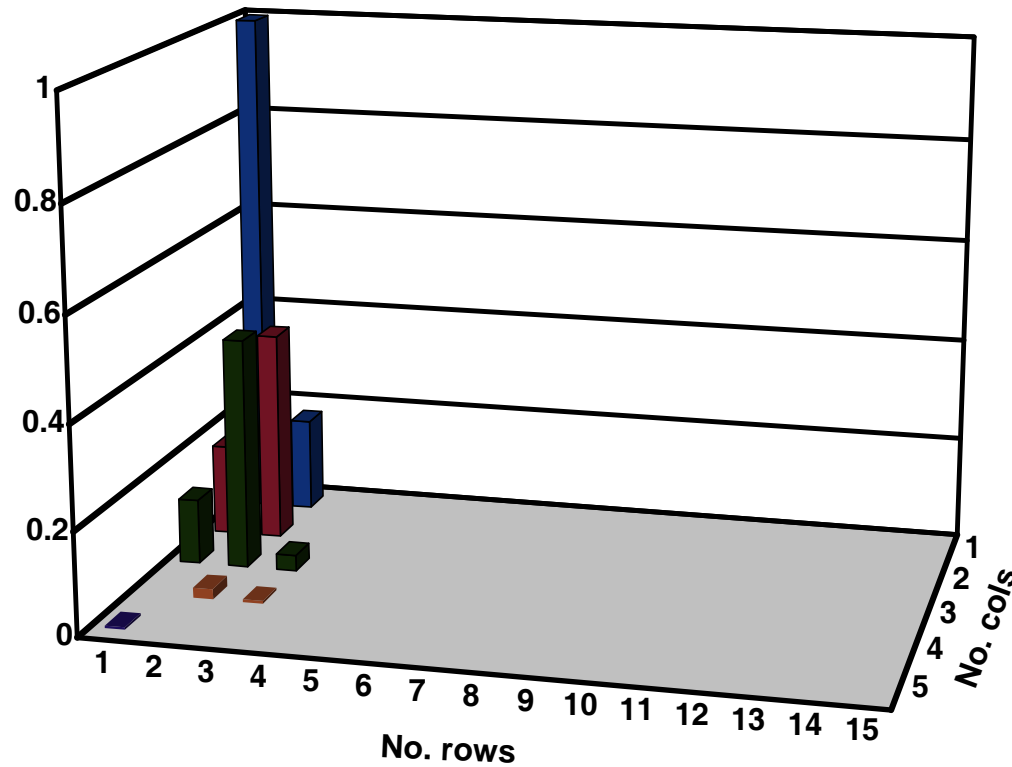


MRED simulated a GEO environment



Omni-directional simulation results

Ar 79° against the wells



Conclusion

- Heavy ion irradiations have been performed
 - SEU varies little with angle of ion incidence
 - MBU depend on the device orientation
- The MBU response depends on the well orientation of the device
- MRED simulation of an omni-directional GEO environment shows the MBU response to be a combination of response from different orientations
- Testing and simulation must account for multiple orientations